

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT3263046

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
TOMOHide TERASHIMA	11/14/2014
YASUHIRO YOSHIURA	11/14/2014
EIKO OTSUKI	11/14/2014
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State/Country:	JAPAN
Postal Code:	100-8310
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14427852
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DATE SIGNED:	03/12/2015
Total Attachments: 1	
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ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

- (1) Tomohide TERASHIMA
- (2) Yasuhiro YOSHIURA
- (3) Eiko OTSUKI

who have made a certain new and useful invention, hereby sell, assign and transfer unto

Mitsubishi Electric Corporation
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its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled

SEMICONDUCTOR DEVICE MANUFACTURING METHOD AND SEMICONDUCTOR MANUFACTURING APPARATUS

for which an application for United States Letters Patent was executed on even date herewith,

and the undersigned hereby authorize and request the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefor and any and all extensions, divisions, reissues, substitutes, renewals, continuations, or continuations-in-part thereof, and the right to all benefits under the international Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agree that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agree to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the dates indicated aside our signatures:

INVENTORS	DATE SIGNED
1) <u>Tomohide Terashima</u> Name: Tomohide TERASHIMA	<u>November 14, 2014</u>
2) <u>Yasuhiro YOSHIURA</u> Name: Yasuhiro YOSHIURA	<u>November 14, 2014</u>
3) <u>Eiko OTSUKI</u> Name: Eiko OTSUKI	<u>November 14, 2014</u>